# TK3A60DA



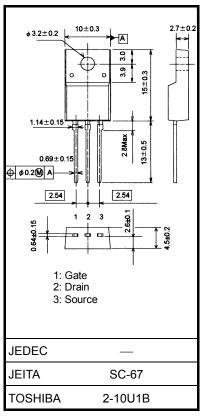
### **Switching Regulator Applications**

Unit: mm

- Low drain-source ON-resistance: RDS (ON) =  $2.2 \Omega(\text{typ.})$
- High forward transfer admittance:  $|Y_{fs}| = 1.5 \text{ S (typ.)}$
- Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 600 \text{ V)}$
- Enhancement mode:  $V_{th} = 2.4 \text{ to } 4.4 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	600	V	
Gate-source voltage		$V_{GSS}$	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	2.5	Α	
	Pulse (Note 1)	I <sub>DP</sub>	10	A	
Drain power dissipation (Tc = 25°C)		PD	30	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	180	mJ	
Avalanche current		I <sub>AR</sub>	2.5	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	3.0	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55 to 150	°C	



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

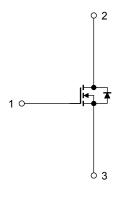
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	4.17	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W



Note 2:  $V_{DD} = 90 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 50 mH,  $R_G = 25 \Omega$ ,  $I_{AR} = 2.5 \text{ A}$ 

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



# **Electrical Characteristics (Ta = 25°C)**

Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rent	I <sub>GSS</sub>	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μΑ
Drain cut-off curr	ent	I <sub>DSS</sub>	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0 V	_	_	10	μА
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	600	_	_	V
Gate threshold ve	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.4	_	4.4	V
Drain-source ON	resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> =1.3 A	_	2.2	2.8	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> =1.3 A	0.4	1.5	_	S
Input capacitance		C <sub>iss</sub>		_	380	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	2.5	_	
Output capacitance		Coss		_	45	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS}$ $V_{DD} \approx 200 \text{ V}$	_	15	_	
	Turn-on time	t <sub>on</sub>			35	_	20
	Fall time	t <sub>f</sub>			7	_	ns
	Turn-off time	t <sub>off</sub>	Duty $\leq$ 1%, $t_W = 10 \mu s$	_	55	_	
Total gate charge		Qg		_	9	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 2.5 \text{ A}$	_	5	_	nC
Gate-drain charge		Q <sub>gd</sub>		_	4	_	

# Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	2.5	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	10	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 2.5 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 2.5 \text{ A}, V_{GS} = 0 \text{ V},$	_	700	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> /dt = 100 A/μs	_	3.5	_	μС

# Marking

